

Application Data Sheet

Application Information

Application Type: Regular

Subject Matter: Utility

Suggested Classification:

Suggested Group Art Unit:

CD-ROM or CD-R?: None

Title: Attachment of Flip-Chips to Substrates

Request for Early Publication?: No

Request for Non-Publication?: No

Suggested Drawing Figure: 4

Total Drawing Sheets: 4

Small Entity: No

Petition included?: No

Secrecy Order in Parent Appl.?: No

Applicant Information

Applicant Authority type: Inventor

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Status: Full Capacity

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Applicant Information

Applicant Authority type: Inventor
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Representative Information

| | |
|---------------------------------|-----------|
| Representative Customer Number: | 000050255 |
|---------------------------------|-----------|

Domestic Priority Information

| Application: | Continuity Type: | Parent Application: | Parent Filing Date: |
|--------------|-------------------|---------------------|---------------------|
| | National Stage Of | PCT/SG2002/000282 | 29 November 2002 |

Assignee Information

Assignee name: Infineon Technologies AG

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